



SPECIFICATION

(Reference sheet)

• Supplier : Samsung electro-mechanics • Samsung P/N : CL10B103KA8NNNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 10nF, ±10%, 25V, X7R, 0603

A. Samsung Part Number

<u>CL</u> <u>10</u> <u>B</u> <u>103</u> <u>K</u> <u>A</u> <u>8</u> <u>N</u> <u>N</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor							
2	Size	0603 (inch c	code)	L: 1.6	6 ± 0.1	mm	W:	0.8 ± 0.1	mm
3	Dielectric	X7R		8	Inner e	electrode	N	i	
4	Capacitance	10 nF			Termir	nation	С	u	
(5)	Capacitance	±10 %			Plating	3	S	n 100%	(Pb Free)
	tolerance			9	Produc	ct	N	ormal	
6	Rated Voltage	25 V		10	Specia	ıl	R	eserved for	future use
7	Thickness	0.8 ± 0.1	mm	11	Packag	ging	C	ardboard T	ype, 7" reel

B. Samsung Reliability Test and Judgement condition

	Performance	Test condition					
Capacitance	Within specified tolerance	1kHz±10% 1.0±0.2Vrms					
Tan δ (DF)	0.025 max.						
Insulation	10,000Mohm or 500Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.					
Resistance	Whichever is Smaller						
Appearance	No abnormal exterior appearance	Microscope (×10)					
Withstanding	No dielectric breakdown or	250% of the rated voltage					
Voltage	mechanical breakdown						
Temperature	X7R						
Characteristics	(From -55℃ to 125℃, Capacitance change should be within ±15%)						
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.					
of Termination	terminal electrode						
Bending Strength	Capacitance change: within ±12.5%	Bending to the limit (1mm)					
		with 1.0mm/sec.					
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder					
	is to be soldered newly	245±5℃, 3±0.3sec.					
		(preheating : 80~120 ℃ for 10~30sec.)					
Resistance to	Capacitance change: within ±7.5%	Solder pot : 270±5℃, 10±1sec.					
Soldering heat	Tan δ, IR : initial spec.						

	Performance	Test condition			
Vibration Test	Capacitance change : within ±5%	Amplitude : 1.5mm			
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)			
		2hours × 3 direction (x, y, z)			
Moisture	Capacitance change: within ±12.5%	With rated voltage			
Resistance	Tan δ : 0.05 max	40±2℃, 90~95%RH, 500+12/-0hrs			
	IR: 500Mohm or 25Mohm ⋅ μF				
	Whichever is Smaller				
High Temperature	Capacitance change : within ±12.5%	With 200% of the rated voltage			
Resistance	Tan δ : 0.05 max	Max. operating temperature			
	IR: 1000Mohm or 50Mohm · μF				
	Whichever is Smaller	1000+48/-0hrs			
Temperature	Capacitance change : within ±7.5%	1 cycle condition			
Cycling	Tan δ, IR : initial spec.	Min. operating temperature → 25 °C			
		→ Max. operating temperature → 25°C			
		5 cycle test			

C. Recommended Soldering method:

Reflow (Reflow Peak Temperature : 260+0/-5°C, 10sec. Max)



A Product specifications included in the specifications are effective as of March 1, 2013.

Please be advised that they are standard product specifications for reference only.

We may change, modify or discontinue the product specifications without notice at any time.

So, you need to approve the product specifications before placing an order.

Should you have any question regarding the product specifications,

please contact our sales personnel or application engineers.